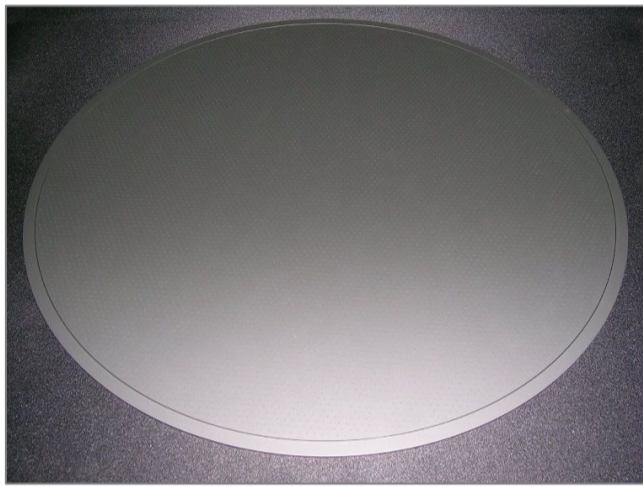


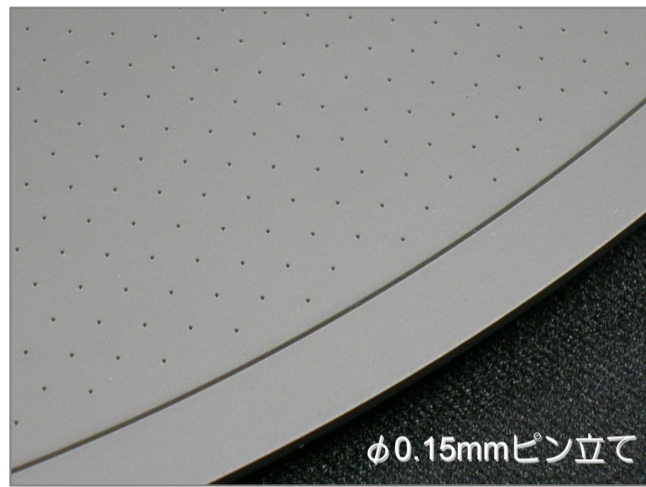
超精密微細パターン加工／高密度SiCパーツ

“Ultra-Precision Machining and Micromachining of SiC”

微細ピン(凸)を形成したSiC基板の超平坦化仕上げ加工。
 Fine pins are formed on the surface of SiC substrate, which is mechanically planarized with ultra-high accuracy.



Size: $\phi 310 \times t1.5$ mm ($\phi 12.2 \times t0.06$ ")
 Material: Sintered SiC (Silicon Carbide)

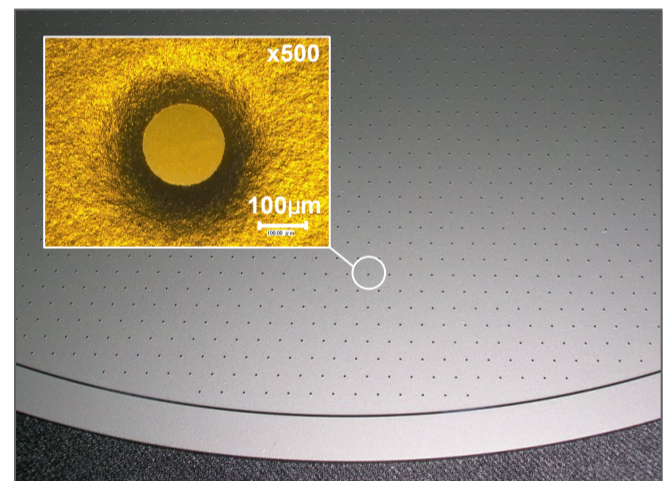


Pin Pattern: Pitch2.5- $\phi 0.15 \times h0.1$ mm
 (Pitch0.1- $\phi 0.006 \times h0.04$ ")

製品特長

Product Features

- ▶ ピン径 $\phi 0.1$ mmから製作可能
 Pin sizes available from 0.004" in diameter.
- ▶ ピンの面積占有比率1%以下
 Occupancy ratio of pins is less than 1% of the surface.
- ▶ 全面平面度 $0.3 \mu\text{m}$ 以下 (300mm面内)
 Total surface flatness less than 12 μ " (12" in-plane).
- ▶ 消耗面の再生加工可能
 Recycle service available for consumed surface.



平面度測定結果

Flatness Measurements

→ Example of Application to Vacuum Pin Chuck (12")

測定器：レーザー干渉計 / FUJINON G310
 Measuring Instrument : LASER INTERFEROMETER

測定方法：Siウェーハ(300mm)を吸着し、ウェーハ全面についてPV測定
 Measurement Means : Flatness is measured on the total surface of Si wafer(12") which is adsorbed on vacuum pin chuck.

全面平面度： **PV=0.181 μm**
 Total Surface Flatness : **PV=7.13 μ "**

